



Product End-of-Life Disassembly Instructions

Product Category: Workstation

Marketing Name / Model

[List multiple models if applicable.]

HP Z2 Tower G9 Workstation Desktop PC/ FCW-F001MT-700&FCW-F001MT-500&FCW-F001MT-450&FCW-F001MT-350

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB*1 <input checked="" type="checkbox"/> Solid state drive (SSD) PCB*1 <input type="checkbox"/> Wireless WAN module (WWAN) PCB <input type="checkbox"/> Touch module PCB <input checked="" type="checkbox"/> Power supply PCB*6 <input checked="" type="checkbox"/> External Keyboard (KB)*1 <input checked="" type="checkbox"/> External Mouse*1 <input checked="" type="checkbox"/> Memory PCB*2 <input checked="" type="checkbox"/> Graphic card PCB*1	13
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input checked="" type="checkbox"/> RTC/CMOS battery <input type="checkbox"/> Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <input type="checkbox"/> screws <input type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input type="checkbox"/> Panel LCD	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input checked="" type="checkbox"/> Power Supply capacitor(s) or condenser(s)	1
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	Philip #0
Screwdriver	Torx T8
Heatgun	N/A
Suction cup	N/A

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Open and remove the access panel.
2. Remove the front bezel.
3. Disconnect the ODD SATA/ Power cable from.
4. Remove the ODD.
5. Press the button and remove the ODD cage.
6. Use Philip #0 screwdriver to remove the screws.
7. Use Philip #0 screwdriver to remove the screws and remove the support cage.
8. Remove the HDD tray.
9. Disconnect all other cables from motherboard.
10. Remove speaker from Chassis.
11. Remove the SSD from motherboard. SSD PCB area >10 sq cm
12. Remove 2 pcs memories from motherboard.
13. Use Philip #0 screwdriver to remove the screws on the PSU Chassis.
14. Press the PSU's latch on chassis and remove the PSU from chassis.
15. Remove the PCI slot covers (x2) from chassis.
16. Figure16 Press the button and remove the graphic card from Motherboard. See below GFX PCB area >10 sq cm.
17. Press the button and remove the heat sink.
18. Remove the battery from motherboard.
19. Disconnect the cable and use Philip #0 screwdriver to loosen the screws and remove the fan.
20. Disconnect the cable and use Philip #0 screwdriver to loosen the screws.
21. Remove the cooler.
22. Use Philip #0 screwdriver to loosen the screws and separate the fan from cooler.
23. Rotate the handle and open it up.
24. Remove the CPU from motherboard.
25. Press the button and remove antenna cover.
26. Use Philip #0 screwdriver to loosen the screws.
27. Figure27 Use Philip #0 screwdriver to loosen the screws remove the WLAN card from chassis.
28. Use Philip #0 screwdriver to loosen the screws of MB from board and remove the motherboard from chassis.
29. Remove screw for case top.
30. Remove screw for case side.
31. Remove screw for case side.
32. Disconnect fan connector, cable connector (CN1 \ CN4) and remove cable tie.
33. Remove FG screw and PCB screw.
34. Remove PCBA away from bottom chassis.
35. Remove AC inlet.
36. Remove fan.
37. Identity PCBA > 10 cm² for further treatment (main board: 121.5 cm²).
38. Identity PCBA > 10 cm² for further treatment (main board: 16.3437 cm²).
39. Identity PCBA > 10 cm² for further treatment (main board: 19.795 cm²).
40. Identity PCBA > 10 cm² for further treatment (main board: 29.75 cm²).
41. Identity PCBA > 10 cm² for further treatment (main board: 26.956 cm²).
42. Identity PCBA > 10 cm² for further treatment (main board: 25.76 cm²).
43. Identity electrolyte capacitor > 2.5 cm for further treatment (Length: 5 cm).

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](https://www.hp.com/End-of-Life-Product-Disassembly-Instructions)

Figure1 Open and remove the access panel.

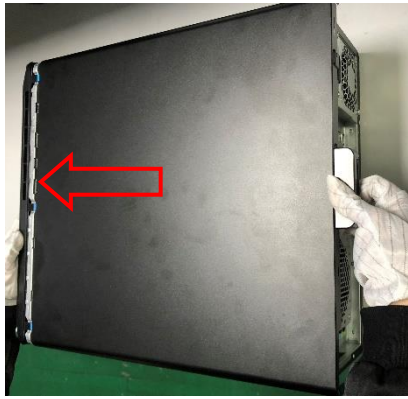


Figure2 Remove the front bezel.

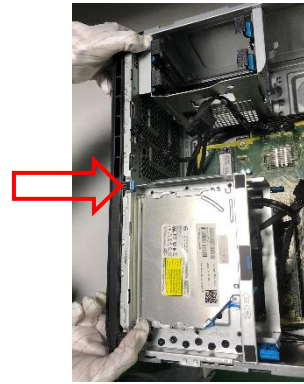


Figure3 Disconnect the ODD SATA/ Power cable from ODD.



Figure4 Remove the ODD.

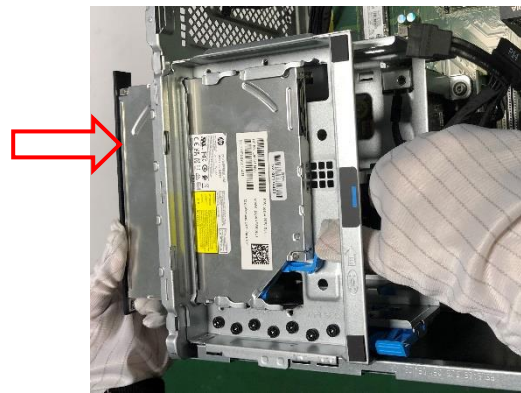


Figure5 Press the button and remove the ODD cage.

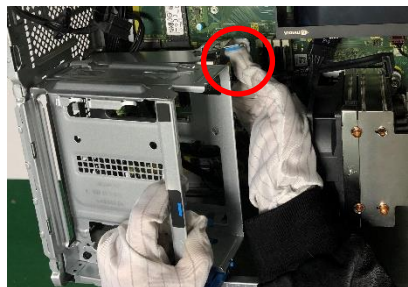


Figure6 Use Philip #0 screwdriver to remove the screws.



Figure7 Philip #0 screwdriver to remove the screws and remove the support cage.

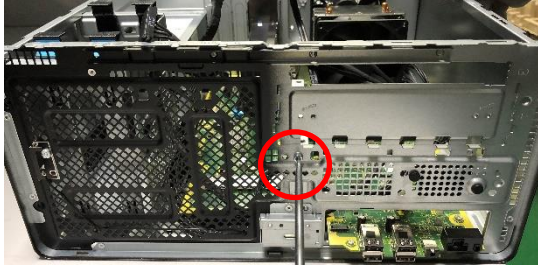


Figure8 Remove the HDD tray.

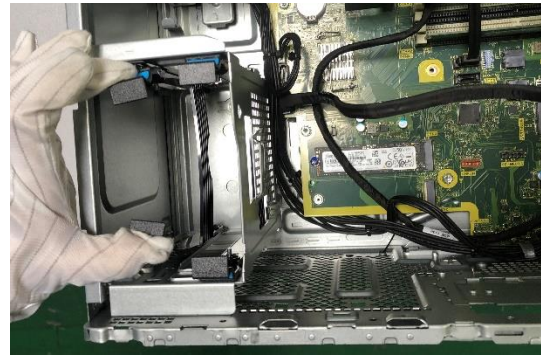


Figure9 Disconnect all other cables from motherboard.

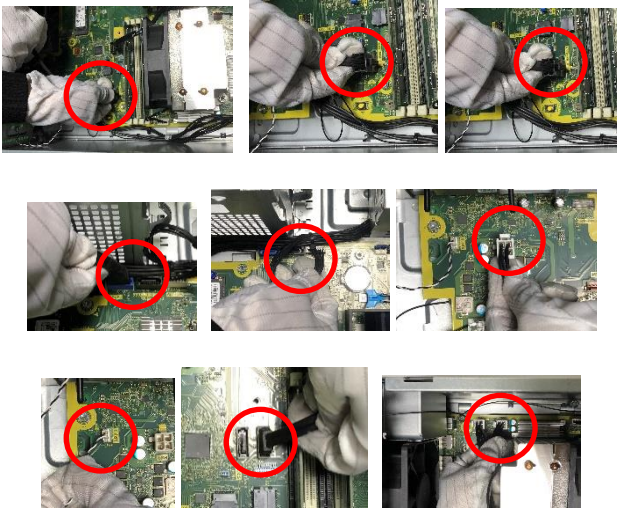


Figure10 Remove speaker from Chassis.

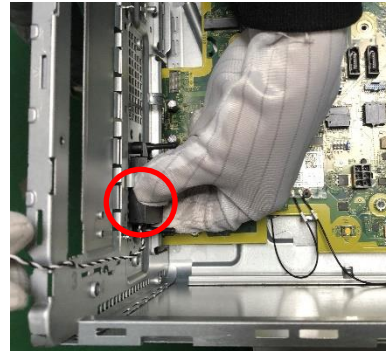


Figure11 Remove the SSD from motherboard. SSD PCB>10 sq cm

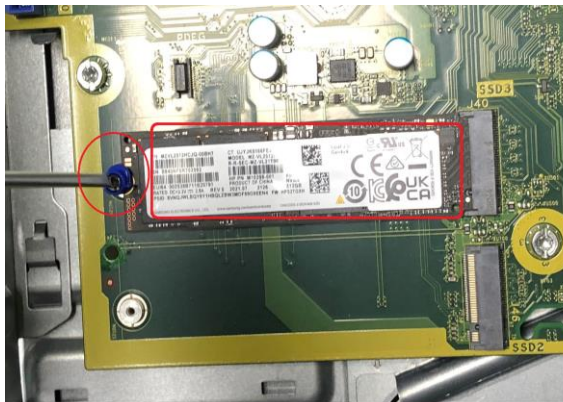


Figure12 Remove 2 pcs memories from motherboard.

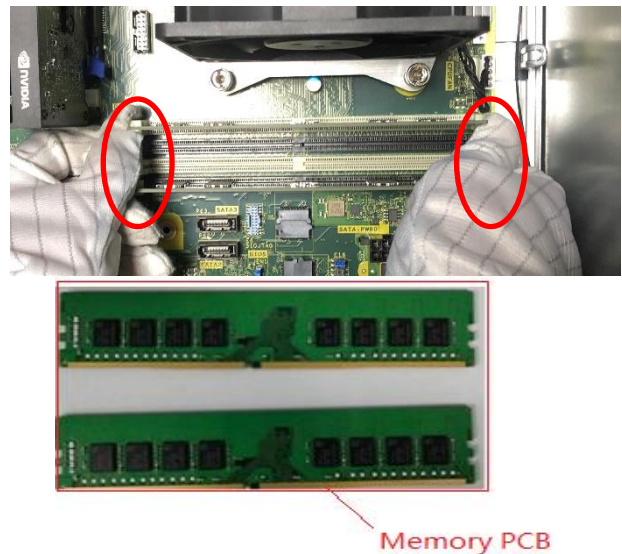


Figure13 Use Philip #0 screwdriver to remove the screws on the PSU Chassis.

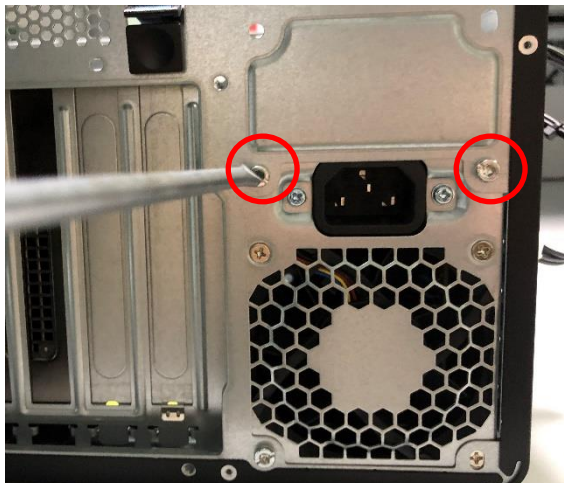


Figure14 Press the PSU's latch on chassis and remove the PSU from chassis.



Figure15 Remove the PCI slot covers (x2) from chassis.



Figure16 Press the button and remove the graphic card from Motherboard. See below GFX PCB >10 sq cm.



Figure17 Press the button and remove the heat sink.

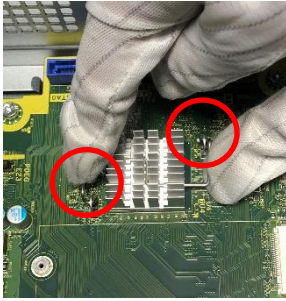


Figure18 Remove the battery from motherboard.

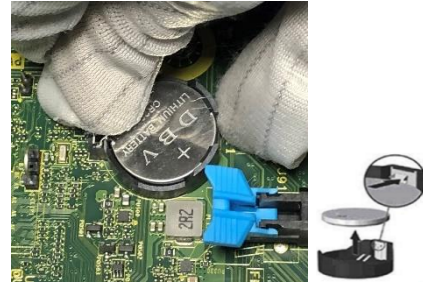


Figure19 Disconnect the cable and use Philip #0 screwdriver to loosen the screws and remove the fan.

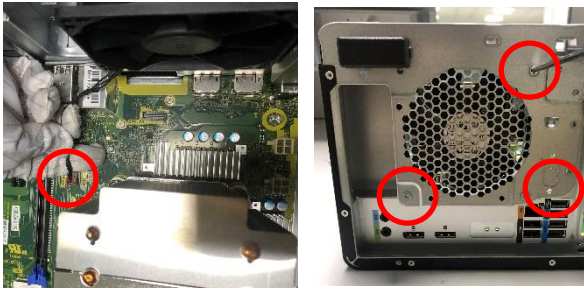


Figure20 Disconnect the cable and use Philip #0 screwdriver to loosen the screws.



Figure21 Remove the cooler.



Figure22 Use Philip #0 screwdriver to loosen the screws and separate the fan from cooler.

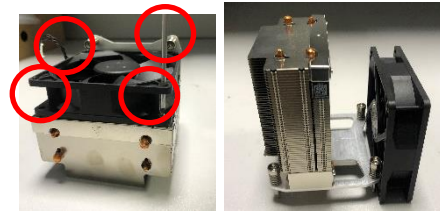


Figure23 Rotate the handle and open it up.



Figure24 Remove the CPU from motherboard.



Figure25 Press the button and remove antenna cover.



Figure26 Use Philip #0 screwdriver to loosen the screws.



Figure27 Use Philip #0 screwdriver to loosen the screws remove the WLAN card from chassis, the PCB >10 sq cm.



Figure28 Use Philip #0 screwdriver to loosen the screws of MB from board and remove the motherboard from chassis.

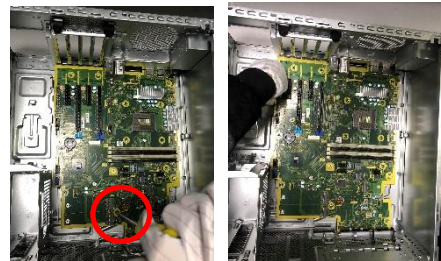


Figure29 Remove screw for case top.



Figure30 Remove screw for case side.

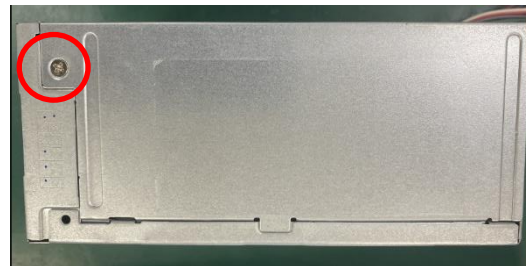


Figure31 Remove screw for case side.

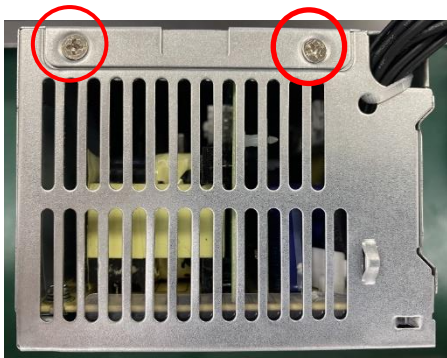


Figure32 Disconnect fan connector, cable connector(CN1、CN4),and remove cable tie.

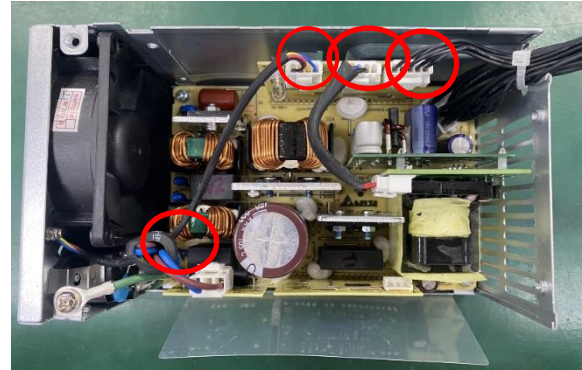


Figure33 Remove FG screw and PCB screw.



Figure34 Remove PCBA away from bottom chassis.

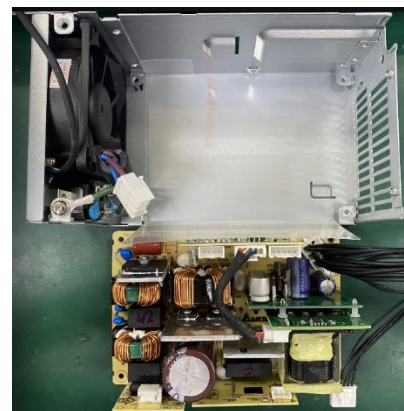


Figure35 Remove AC inlet.

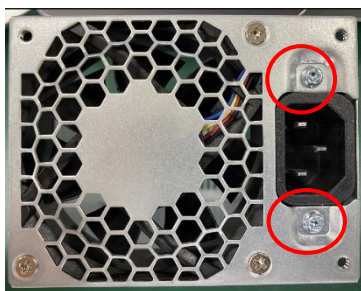


Figure36 Remove fan.

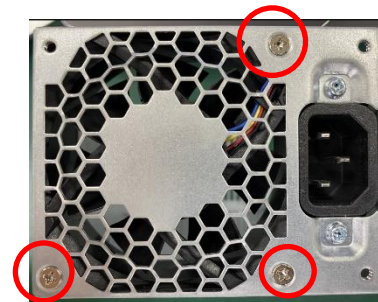


Figure37 Identity PCBA > 10 cm² for further treatment (main board: 121.5 cm²).



Figure38 Identity PCBA > 10 cm² for further treatment (main board: 16.3437 cm²).

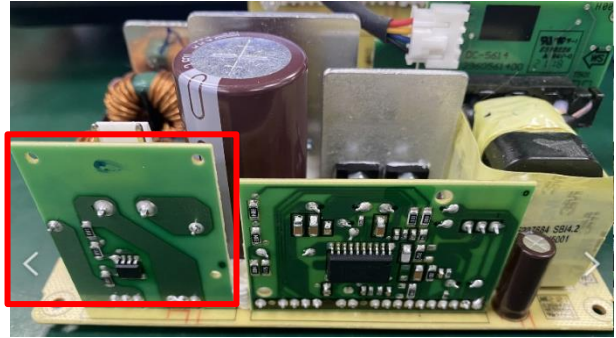


Figure39 Identity PCBA > 10 cm² for further treatment (main board: 19.795 cm²).

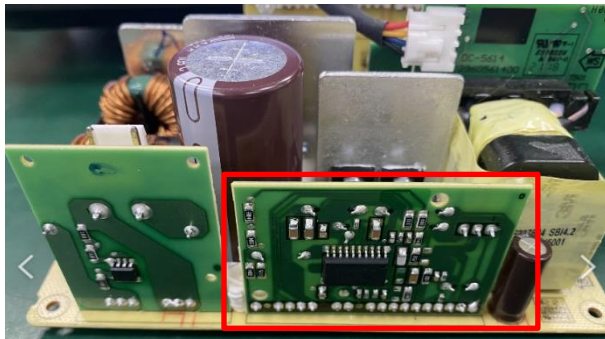


Figure40 Identity PCBA > 10 cm² for further treatment (main board: 29.75 cm²).

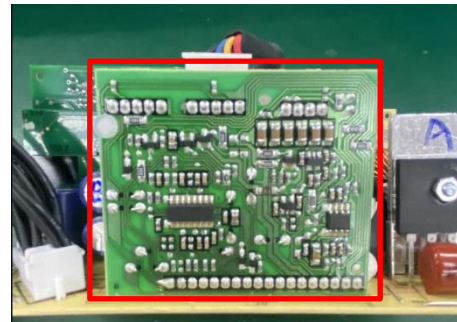
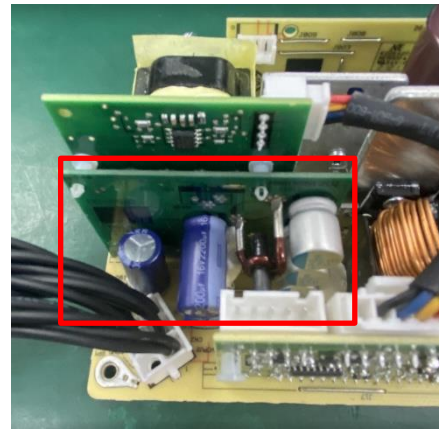


Figure41 Identity PCBA > 10 cm² for further treatment (main board: 26.956 cm²).



Figure42 Identity PCBA > 10 cm² for further treatment (main board: 25.76 cm²).



Step43 Identity electrolyte capacitor > 2.5 cm for further treatment (Length: 5 cm).

